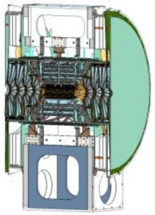
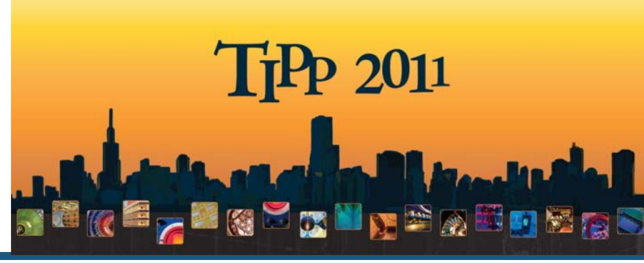
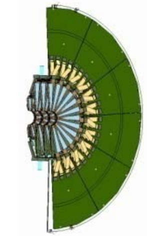






Mechanics and Assembly of the Silicon Vertex Detector for **PHENIX**

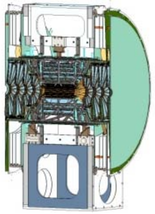
Walter Sondheim - *LANL*

Mechanical Project Engineer; VTX & FVTX Detectors

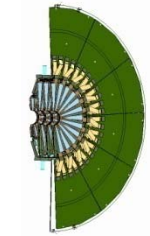
PHENIX

TIPP Conference, June 10, 2011

Los Alamos NATIONAL LABORATORY

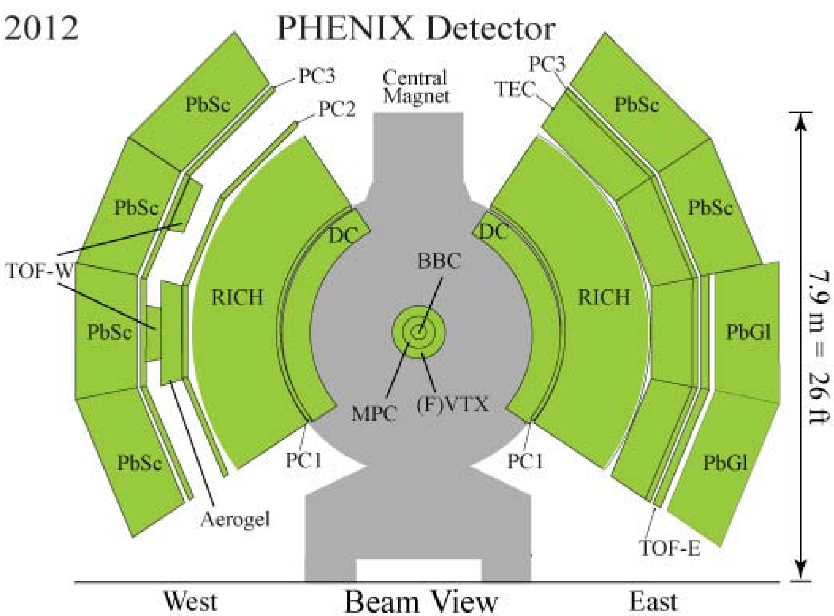


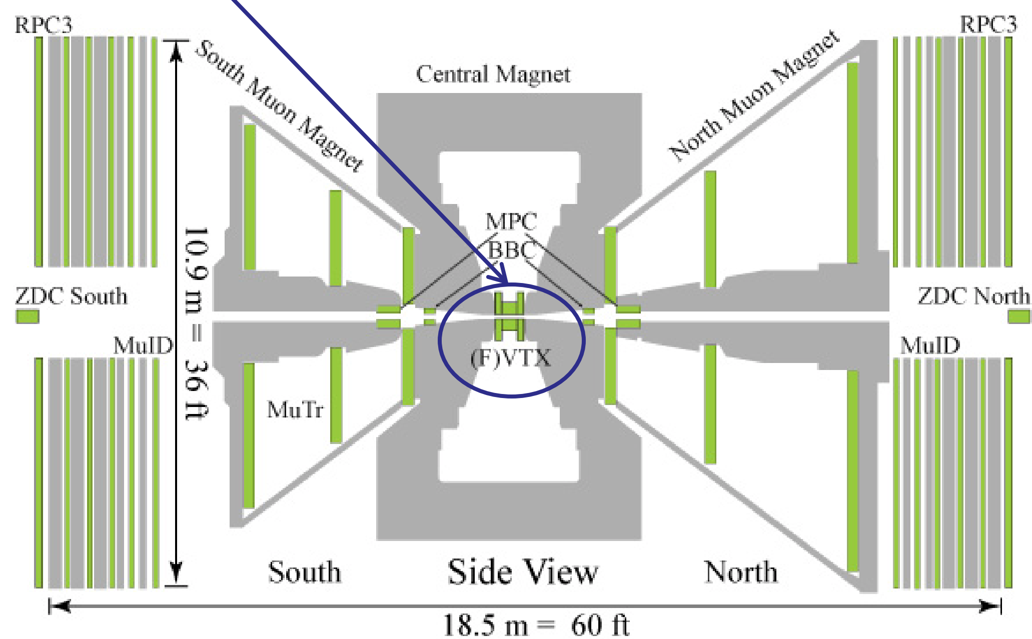
PHENIX Experiment at **RHIC:**



The **PHENIX** experiment at **RHIC** is now in its *11th* year of data taking. Experimental configuration for RUN in 2012:

Vertex Region*

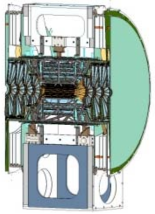




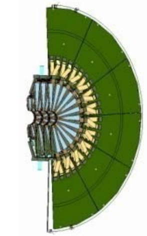
2 central arms; electrons, photons, hadrons

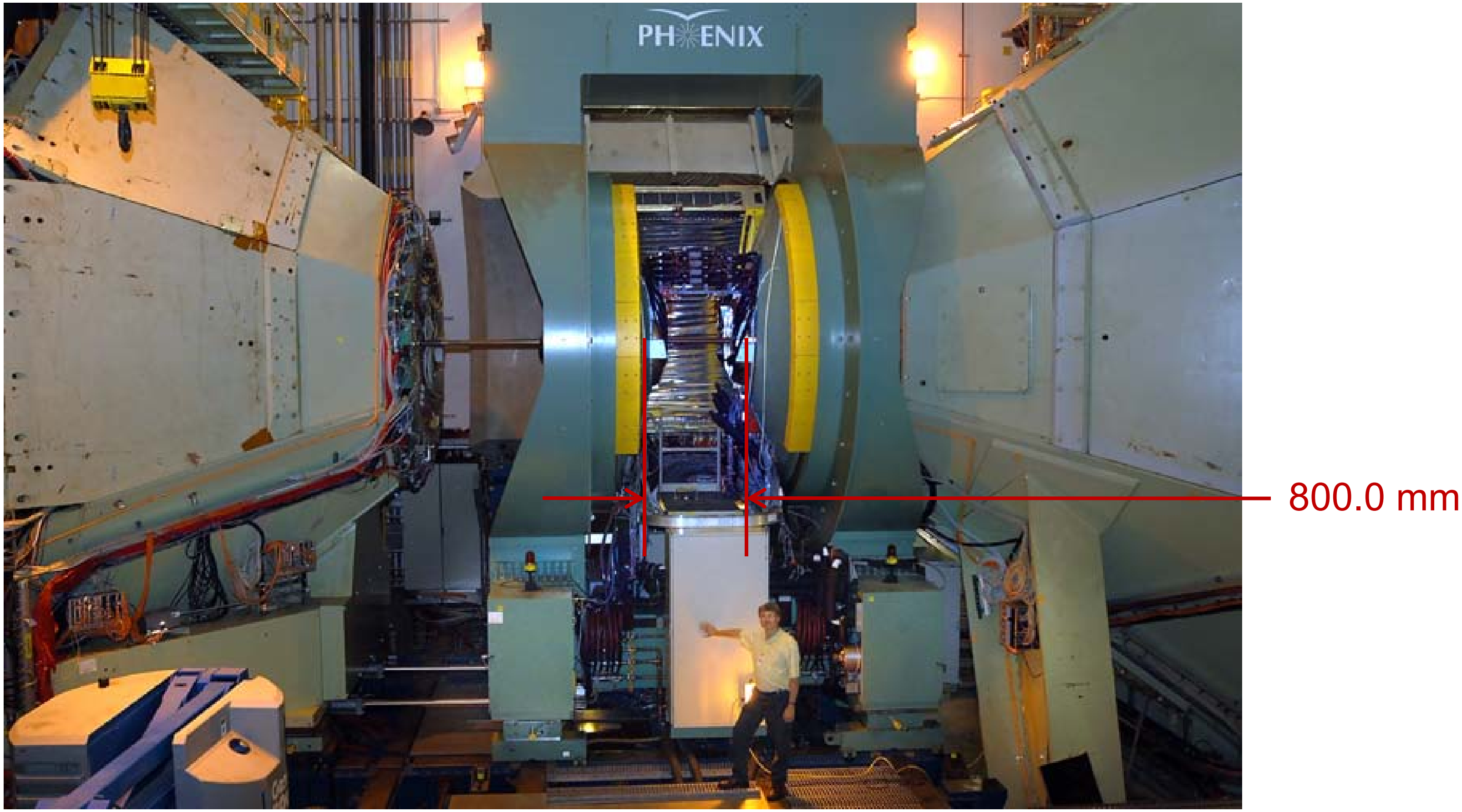
2 muon-spectrometer arms; muons

*VTX installed for current run cycle, FVTX next year's run cycle

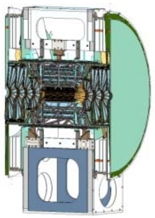


PHENIX Experiment at **RHIC:**

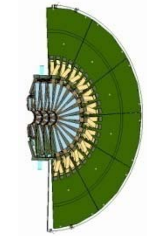




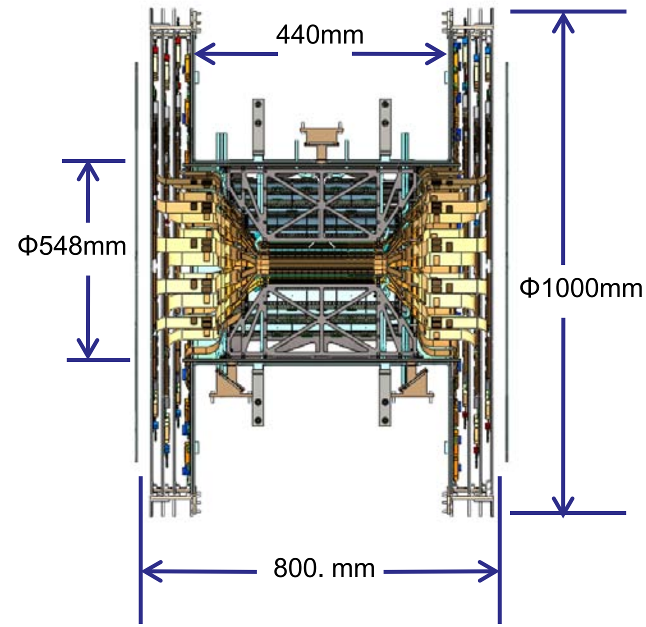
Available space for Vertex Detector 800.0 mm between the Central Magnet pole tips along the beam axis. The original 3.0 inch diameter Beryllium beam pipe was replaced with a 1.575 inch ID x .020 wall NEG coated Beryllium beam pipe, now installed for this run cycle.

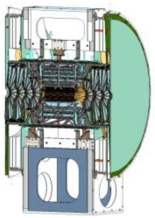


VTX Design Criteria:

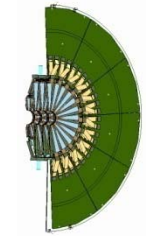


- VTX - Barrel Detector:
  - 2 pixel sensor layers at a radius = 25.0 and 50.0 mm
    - Fine granularity, low occupancy
      - 50µm x 450µm pixel size, ALICE LHCB1 read-out chip
      - AC Coupled read-out, required coolant temp. @ 10°C
        - » To avoid de-lamination
  - 2 stripixel layers at a radius = 100.0 and 140.0 mm
    - Unique sensor design from BNL Instrumentation
      - 80µm x 1000µm pixel pitch, SVX4 read-out chip
      - DC Coupled read-out, required cooling @ 0° C,
        - » Avoid increase leakage current from radiation damage
  - Φ acceptance ~ 2π
  - $|\eta|$ acceptance < 1.2
  - Dimensional structural stability to 25µm

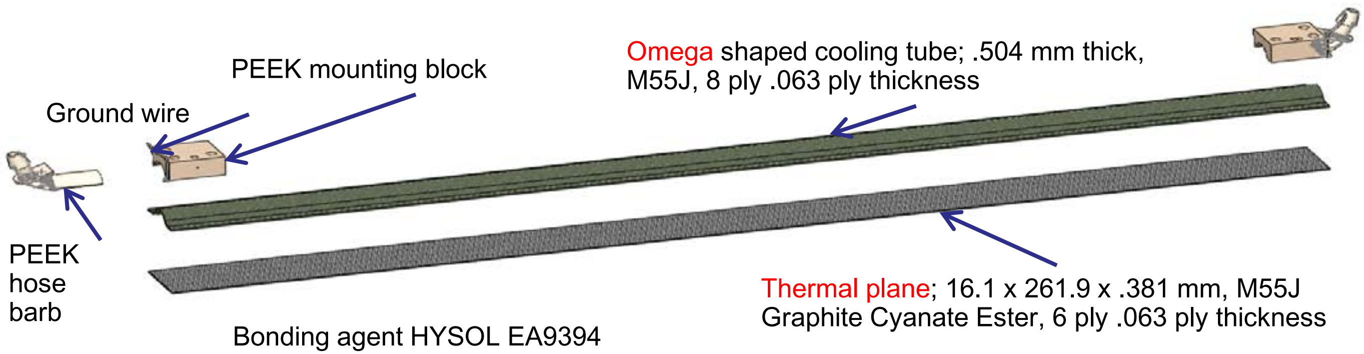




VTX - Pixel layers 1 and 2:

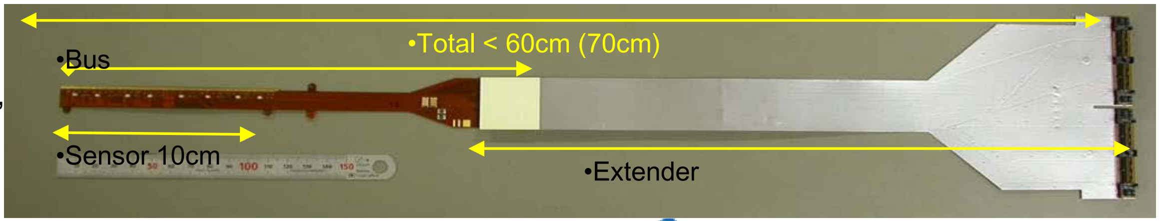


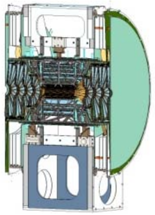
- Closest sensors to beampipe, radiation length should be kept to a minimum
  - Stave design uses Carbon composite technology, Omega shaped bonded to backside of thermal plane to create cooling channel. Bonded assembly must meet mechanical tolerance for flatness of 100. microns prior to bonding of sensor modules
  - Layers 1 & 2; 4 sensor modules per ladder, Layer 1 - 5 ladders layer 2 - 10 ladders per half barrel



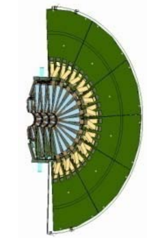
Assembled pixel stave: stave + sensors + readout chips + bus, readout is split in half – left bus and a right bus

Assembled pixel stave with bus extender attached, interface with SPIRO readout card

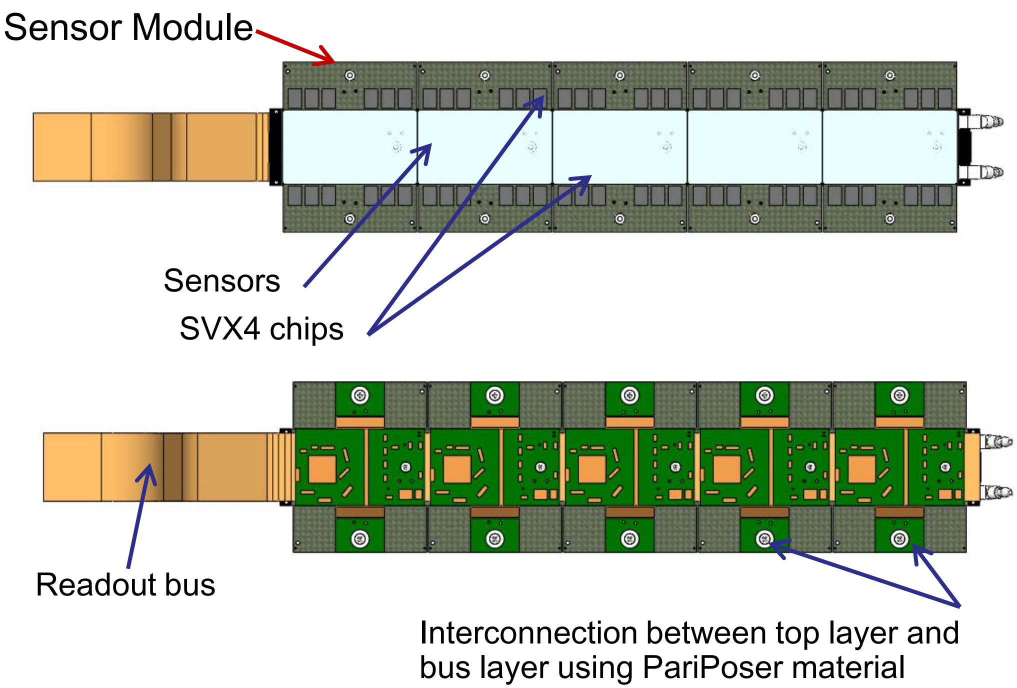


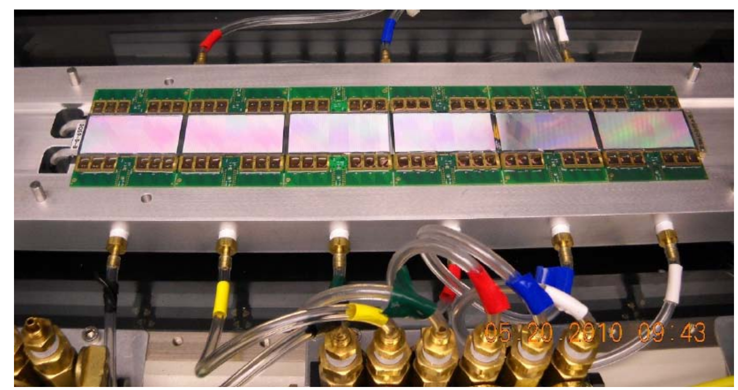


VTX - Stripixel layers 3 and 4:

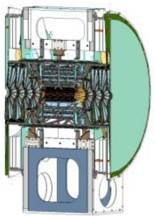


- Improve track segment construction
  - BNL sensor design provides 2 dimensional, single sided readout
  - Readout uses FNAL’s SVX4 chip; 128 channels per chip, 340K channels for layers 3 & 4
  - Layer 3; 5 sensor modules per ladder, 8 ladder assemblies per half barrel
  - Layer 4; 6 sensor modules per ladder, 12 ladder assemblies per half barrel

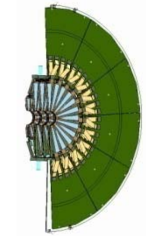




Layer 4 stave with sensor modules being located on stave using vacuum tooling, prior to bonding



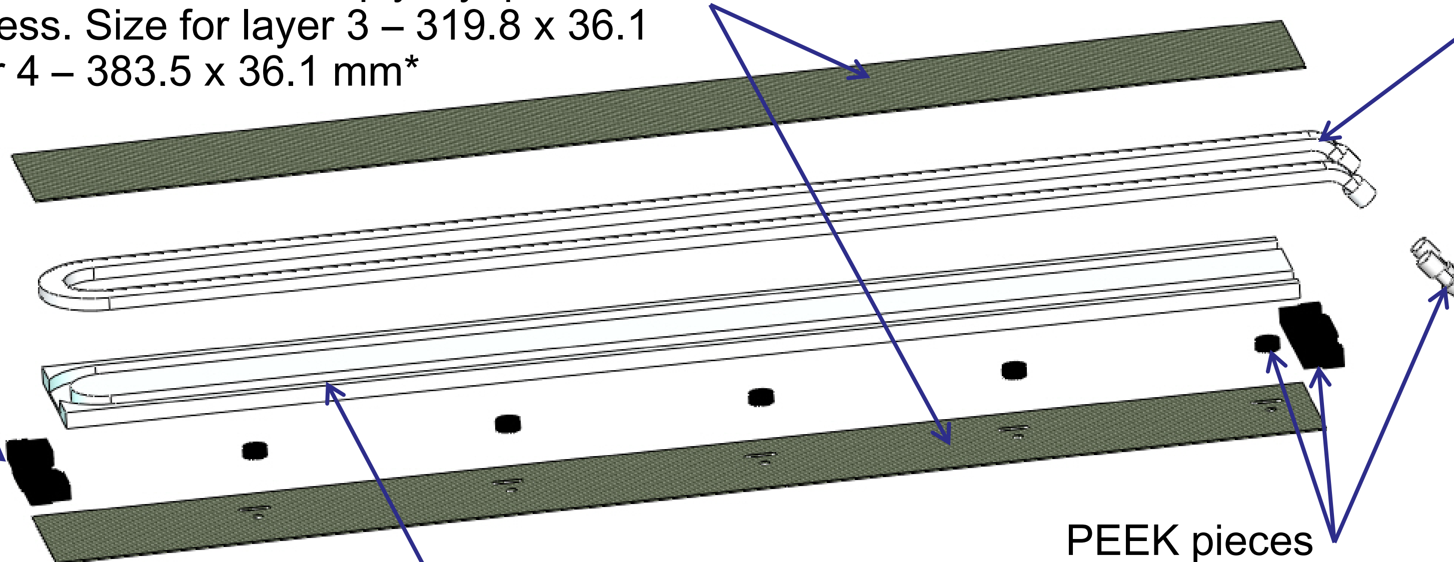
Stripixel stave construction:



Layer 3 & 4 stave assembly: designed to allow for individual electronic modules and bus to be mechanically attached to stave backside – not bonded.

Face Sheets; K13D2U with EX1515 Cyanate Ester resin, .408mm thick, 6 ply layup, .063 ply thickness. Size for layer 3 – 319.8 x 36.1 mm, layer 4 – 383.5 x 36.1 mm*

Aluminum rectangular cooling tube; 3.18 x 6.35 x .38 wall (mm)



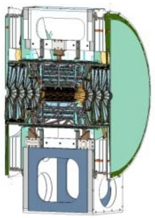
Aluminum end-block, grounds cooling tube

PEEK pieces

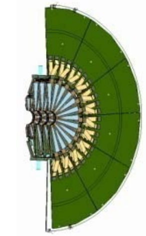
Carbon Foam Core; Allcomp K3, 4.2mm thick

Bonding agent HYSOL EA9396

*Layer 3 stave shown in exploded view, assembly flatness tolerance 100. microns



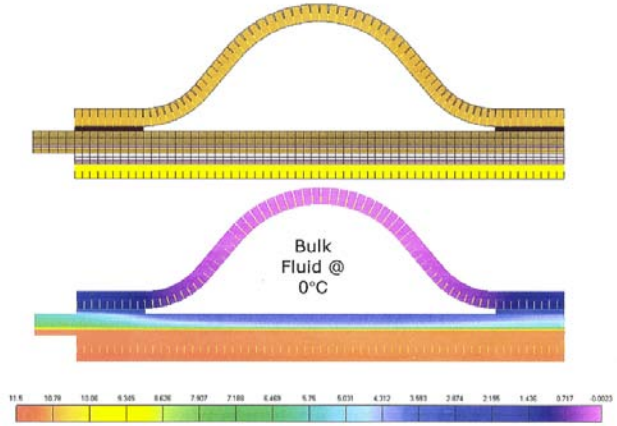
Thermal/Mechanical analysis:



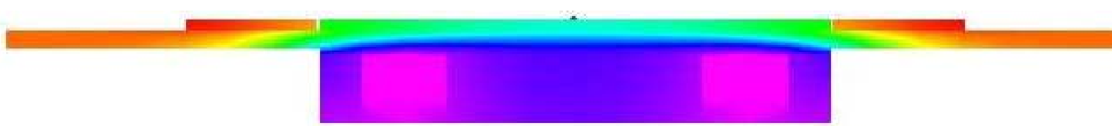
•Pixel stave analysis

- Thermal load for pixel stave is 19.50 watts
- Each ladder's mass summary:
  - Structure/Si-detector/Readout chips 16.4 grams
  - Coolant: 6.5 grams (3M-NOVEC 7200)
  - Total:23.0 grams
  - ΔT:11.5°C*
    - ΔT:23.°C with added metallic tube
  - Gravity sag < 2. microns
  - Pressure tested

*Calculations using Nastran- Mat9 software



Mid-Span Section View

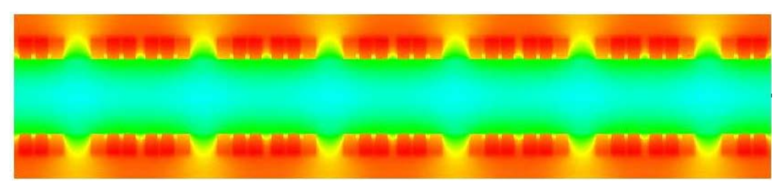


Cross section Temperature profile, layer 4 ladder

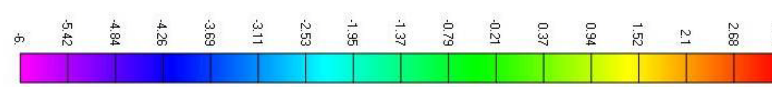
•Stripixel stave analysis

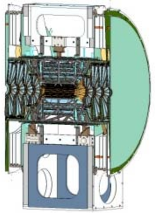
•Design goal to keep DC coupled sensors at 0°C:

- •Coolant wall temperature at -6°C
- •Peak temperature 3.2°C
- •Temperature rise between coolant and sensor 5.55°C

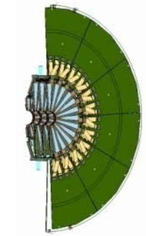


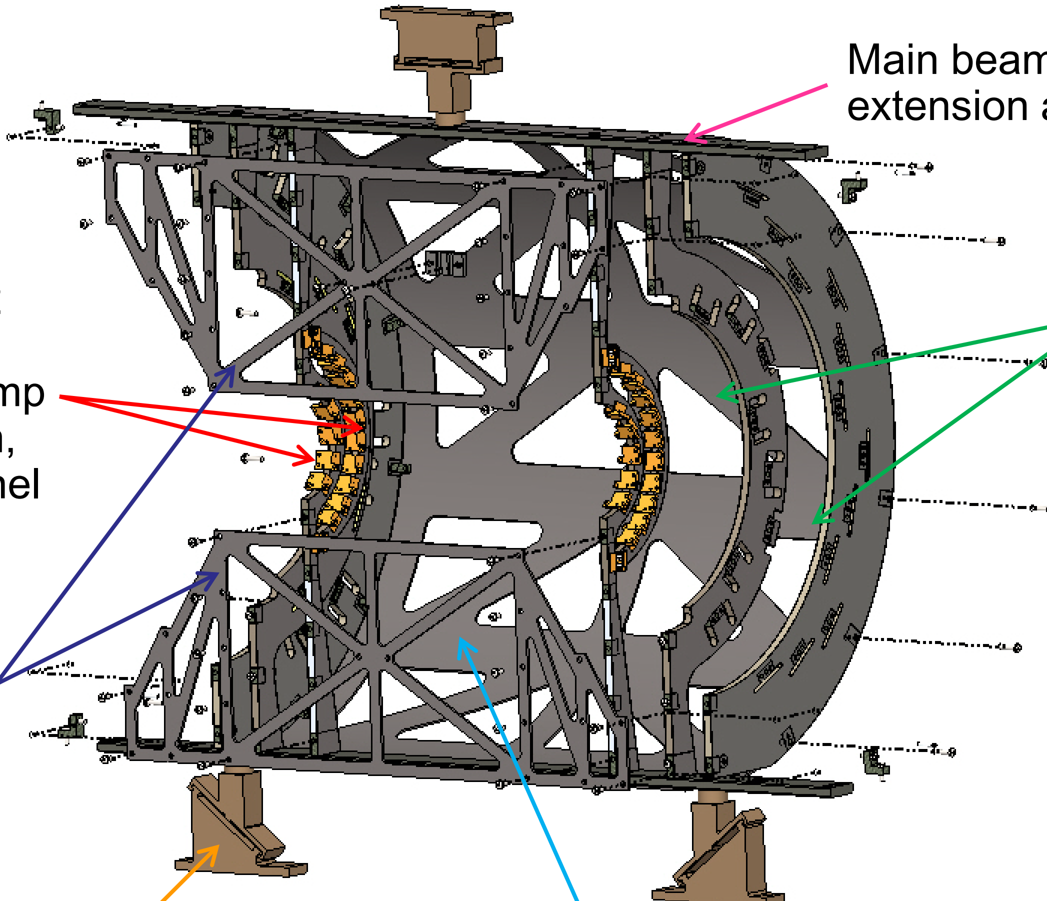
Surface temperature, layer 4 ladder

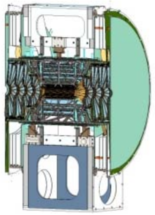




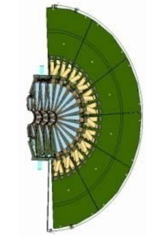
Space-frame and Barrel Mounts, exploded view:

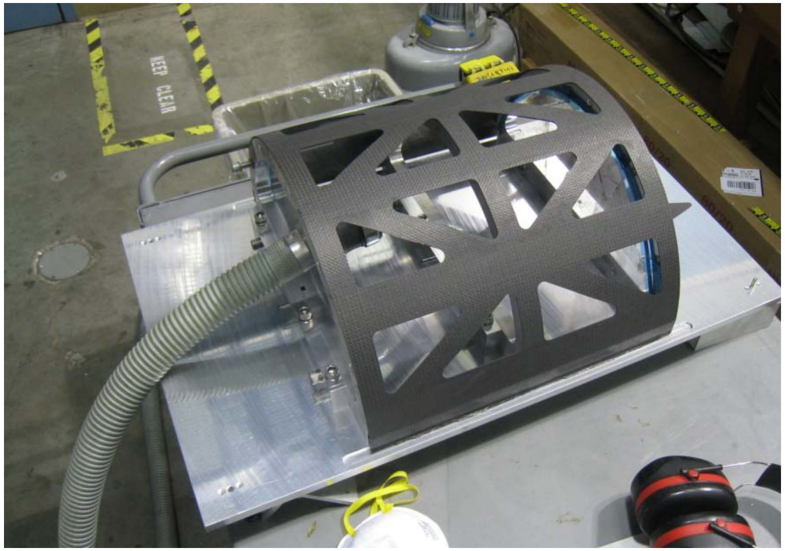




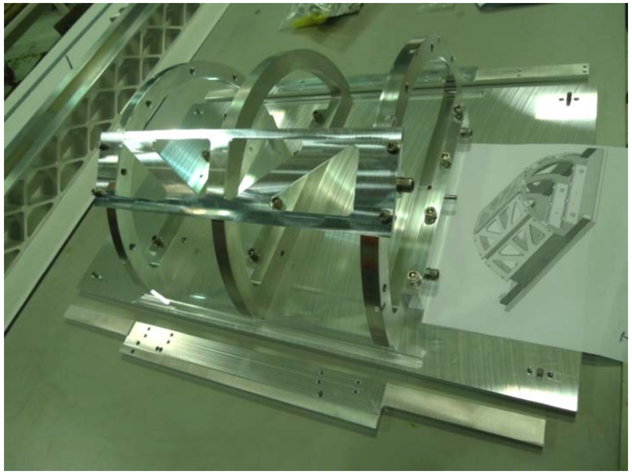


Space-frame component fabrication and assembly:





Space-frame shell: Vacuum jig machining cut-outs

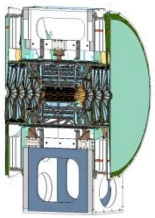


Space-frame shell tooling

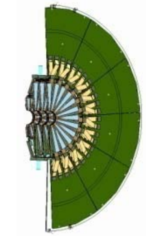
Layer 2 barrel mount on assembly jig

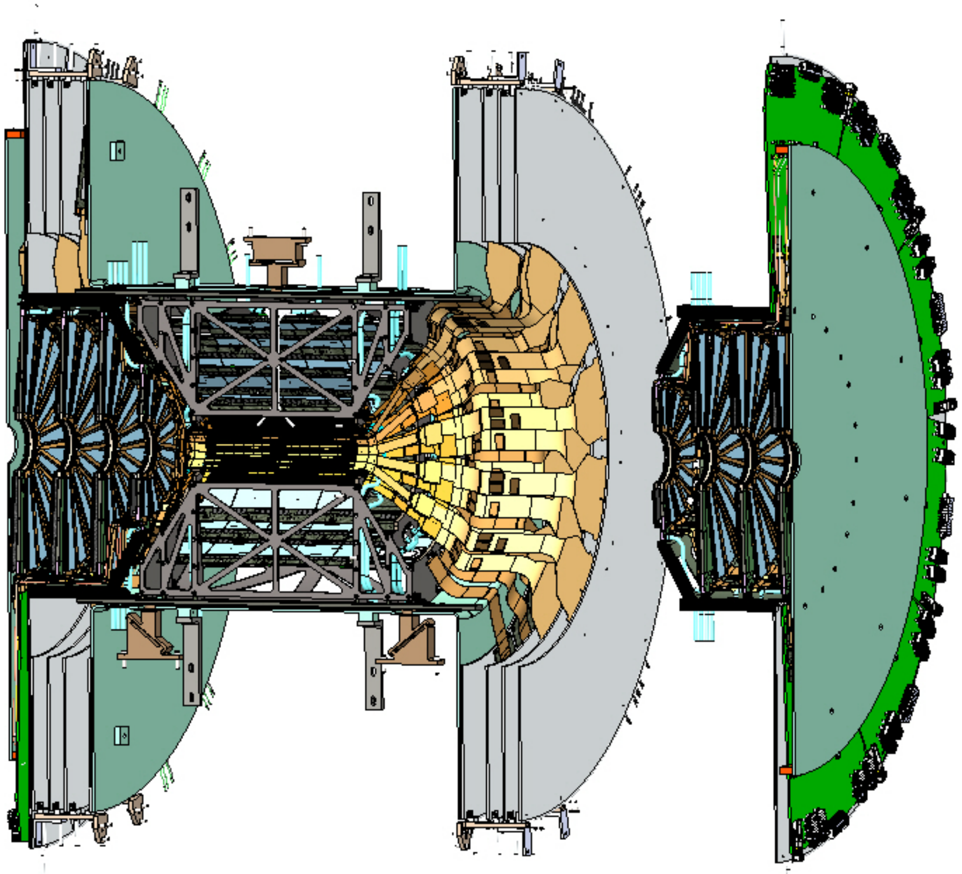
Layer 4 barrel mount on assembly jig

All work at LBNL Composite Shop



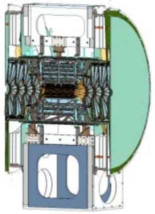
FVTX detector:



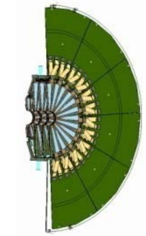


FVTX detector exploded view from VTX assembly

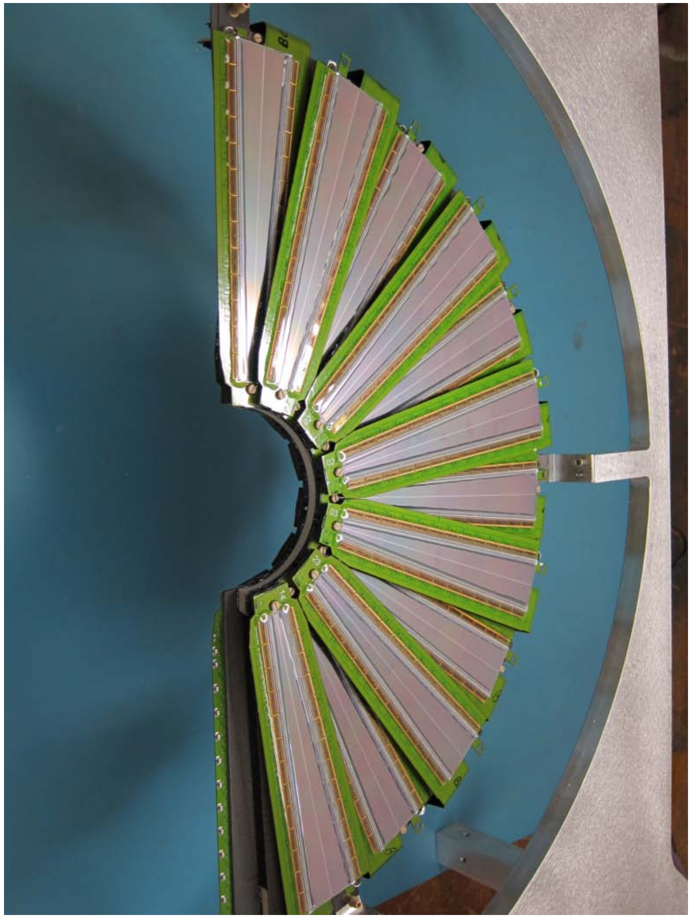
- Silicon tracking in the forward regions of PHENIX;
  - $1.2 < |\eta| < 2.4$
  - Φ acceptance = 2π
- Each FVTX assembly;
  - 4 tracking stations (Disks)
    - Silicon mini-strips, 2.8 – 11.2mm
    - 75. micron pitch (radial direction)
    - FPHX readout chip (FNAL design)
    - ~1.1M channels of readout

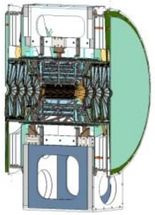


FVTX Station Disks:

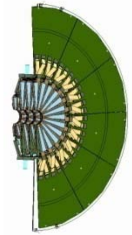


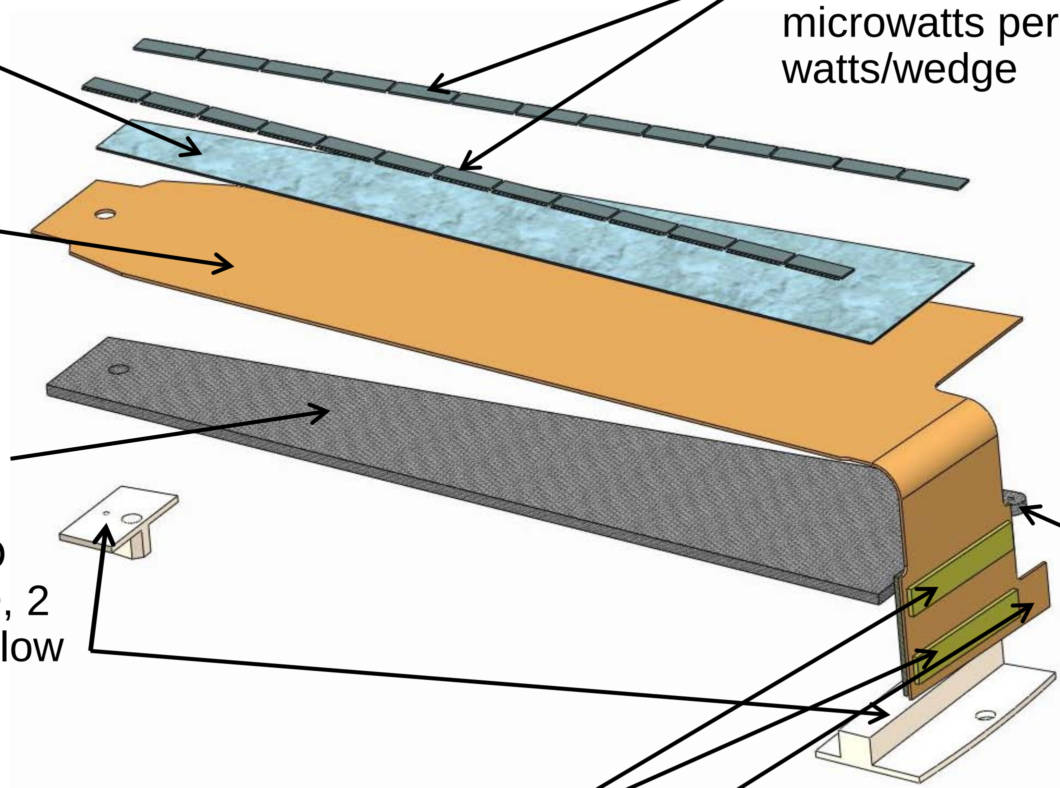
- View of a Station Disk assembly with large Wedges attached to both sides
- Each Wedge covers 15 degrees, each sensor covers 7.5 degrees, Wedges on both sides of Disk staggered by 7.5 degrees front to back – hermetic coverage in phi
- Each disk assembly is pressure tested to 30. psi, cycled 5 times
- The disk assembly bonding agent was Hysol EA9396





Large Wedge construction:





Silicon sensor, 320. microns

FPHX read-out-chips, 13 on each side of sensor, 128 channels each, 410. microwatts per channel, 1.36 watts/wedge

HDI, 334. microns

Each wedge assembly is mounted to a station disk by 2 #2 screws and 2 locating pins

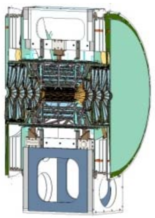
Carbon back-plane, 1.56 mm, K13D2U with EX1515 resin

Spacers – POCO graphite, AXM5Q, 2 versions of each low and high profile

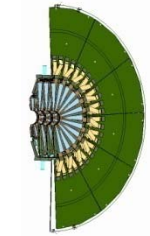
Separate ground connection point for Carbon

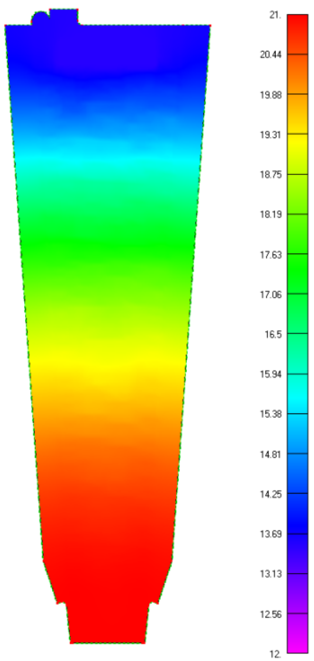
Hirose DF18 series connector, 100 pin for large and 60 pin for small

Hirose H.FL series mini-coax for bias



Large Wedge analysis:



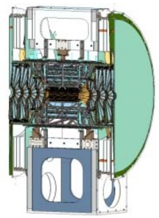


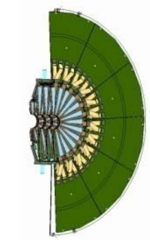
23°
16.5°
12°

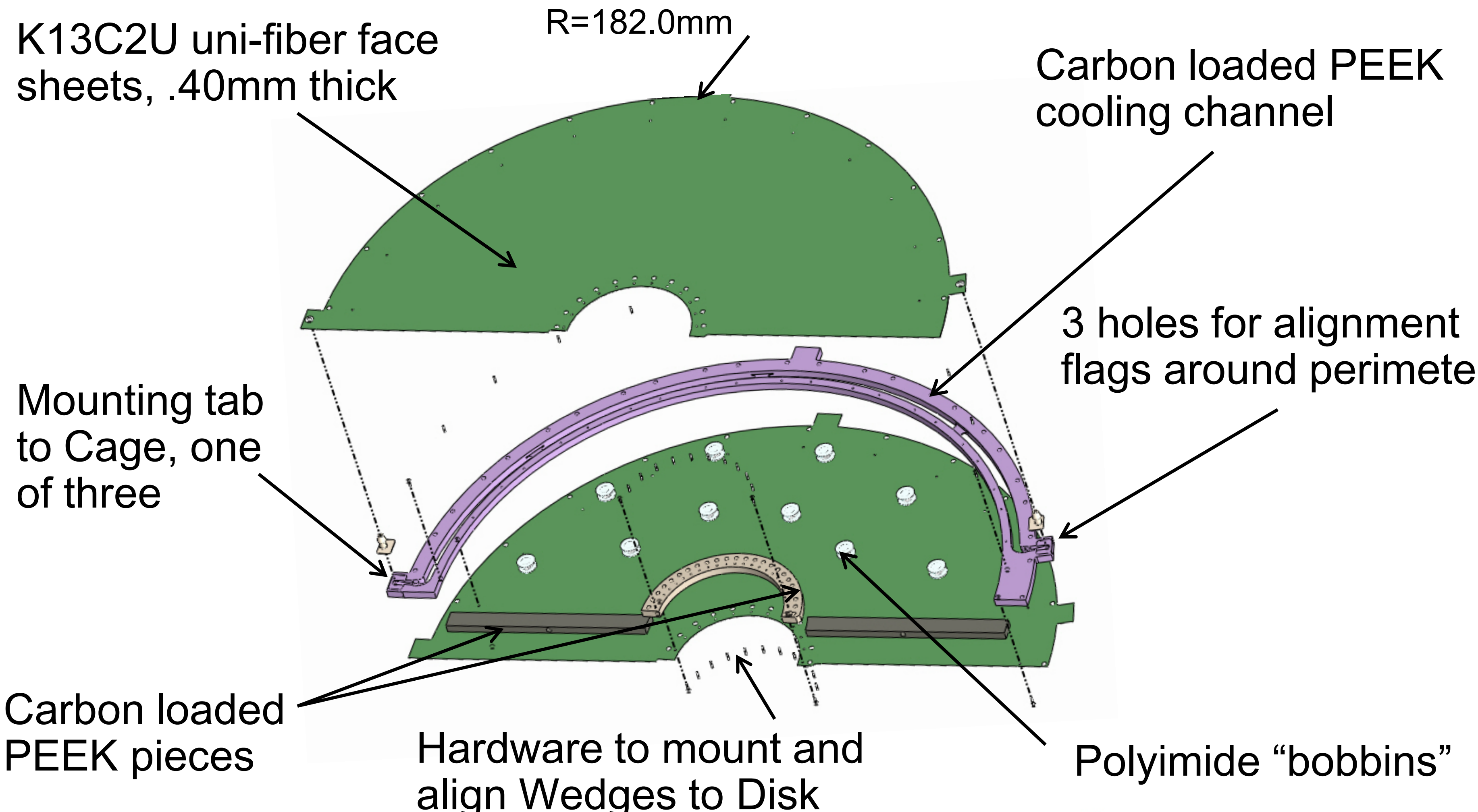
410 μW/Channel
Base Temperature 13.53° C

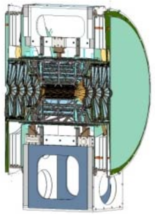
- Thermal path for heat generated on large Wedge
    - Delta T on large Wedge is ~7.47 degrees C
    - Heat from FPHX chips passes through HDI into Carbon backplane – through POCO graphite thermal block to Station Disk where coolant flows around perimeter – NOVEC 7200 coolant
    - Delta T from Disk to Wedge ~ 8. degrees C
    - In analysis a temp constraint was set to keep peak FPHX chip temp at 21 degrees C
    - Bonding of all elements of Wedge assembly, made using Arclad 7876 transfer adhesive, 50. micron thick

Station Disk construction, Stations 2, 3 & 4 Large Disk:

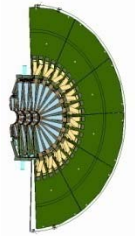


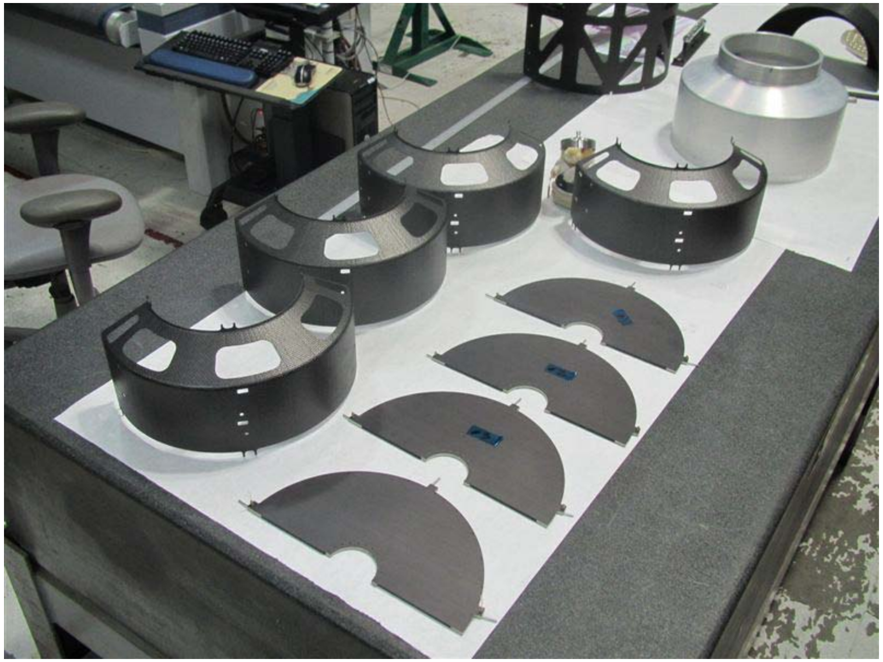




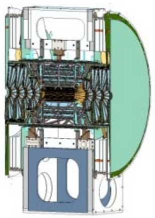


FVTX construction:

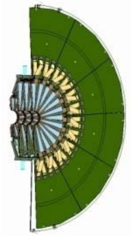


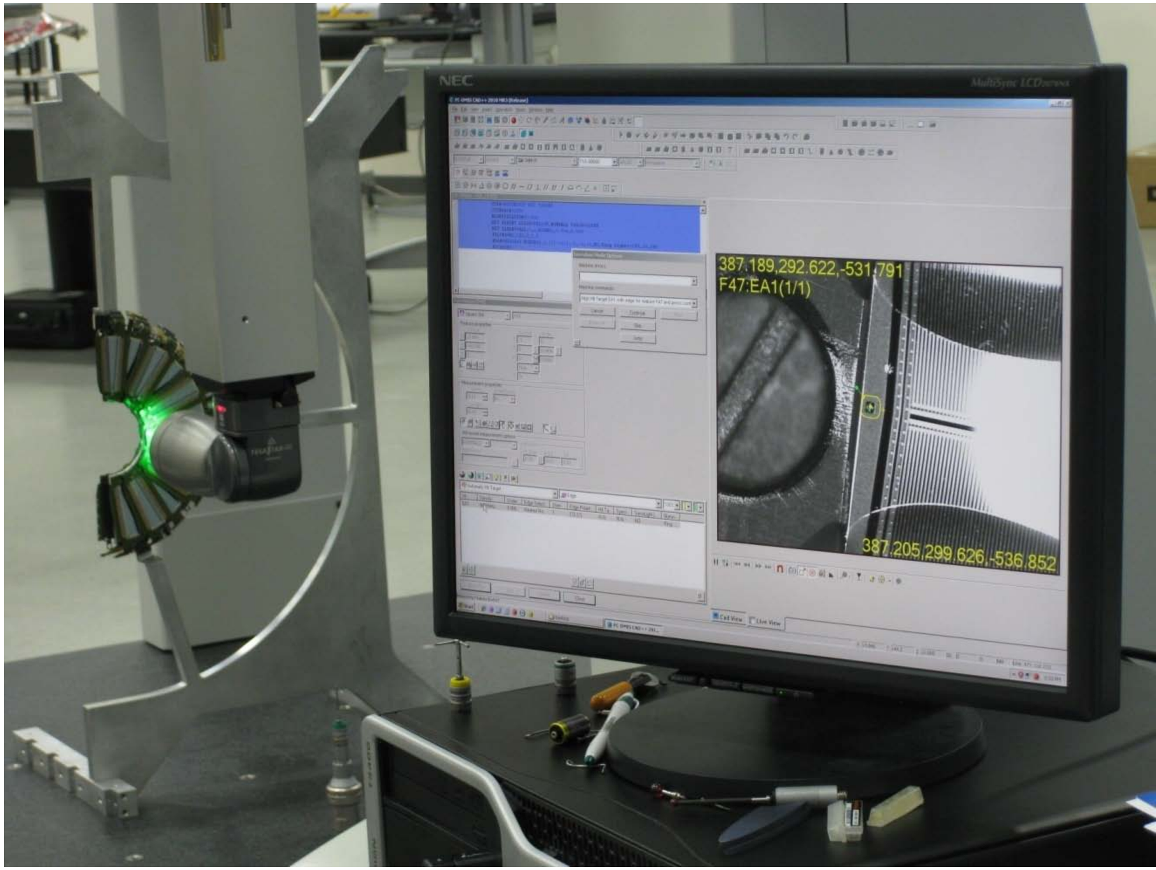


•FVTX cages and station disks being fabricated, tested and assembled at the LBNL composite shop.

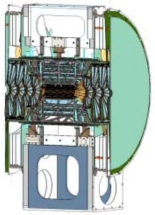


Metrology, FVTX wedge disk:

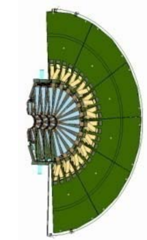


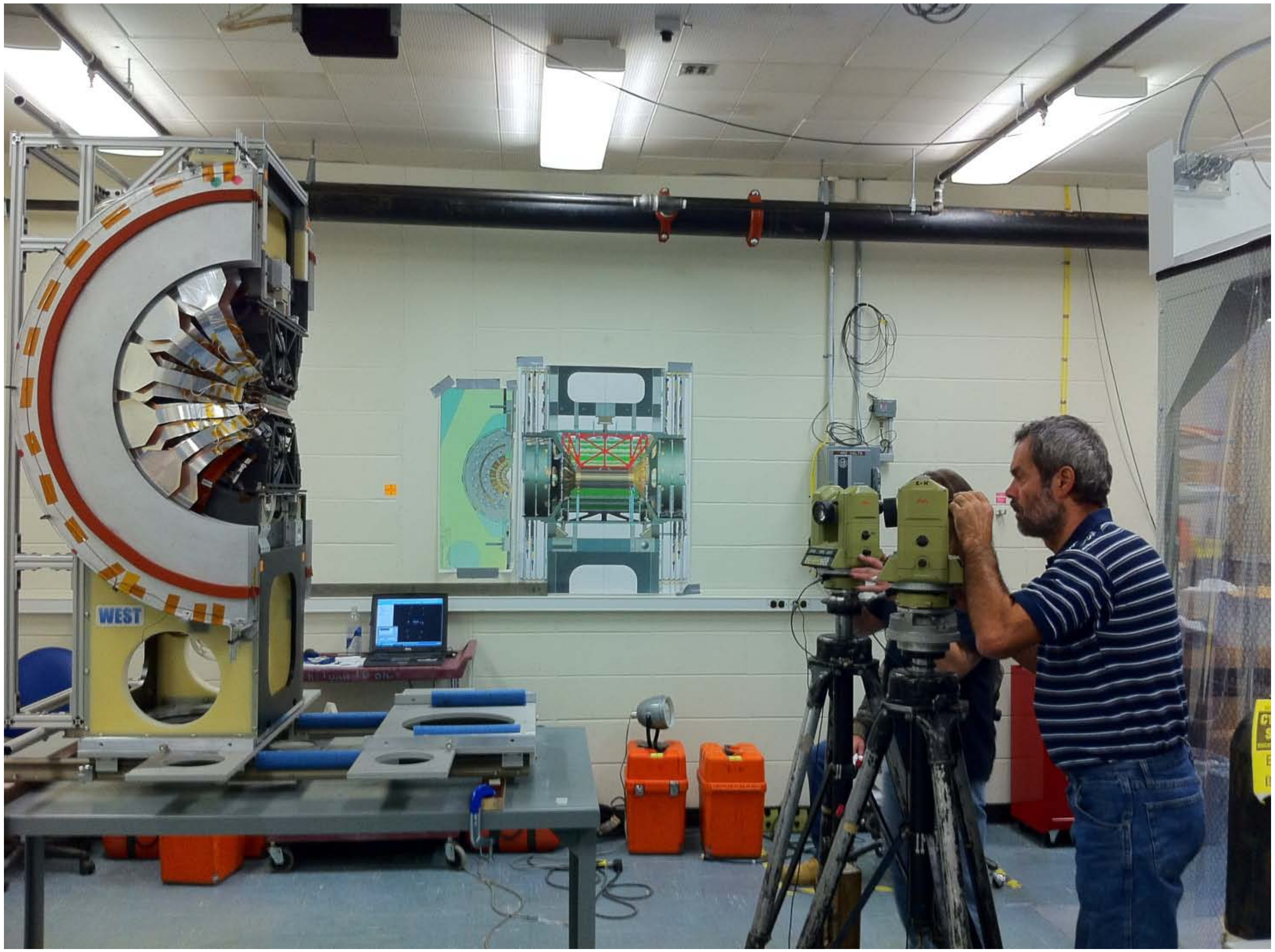


One of 6 -100. micron cross-hair targets on Silicon wedge sensor used to verify relationship of sensors on a disk to 5.08 microns in X-Y and 12.27 microns in Z

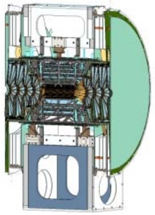


Metrology, Half VTX assembly:

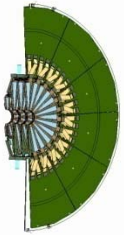


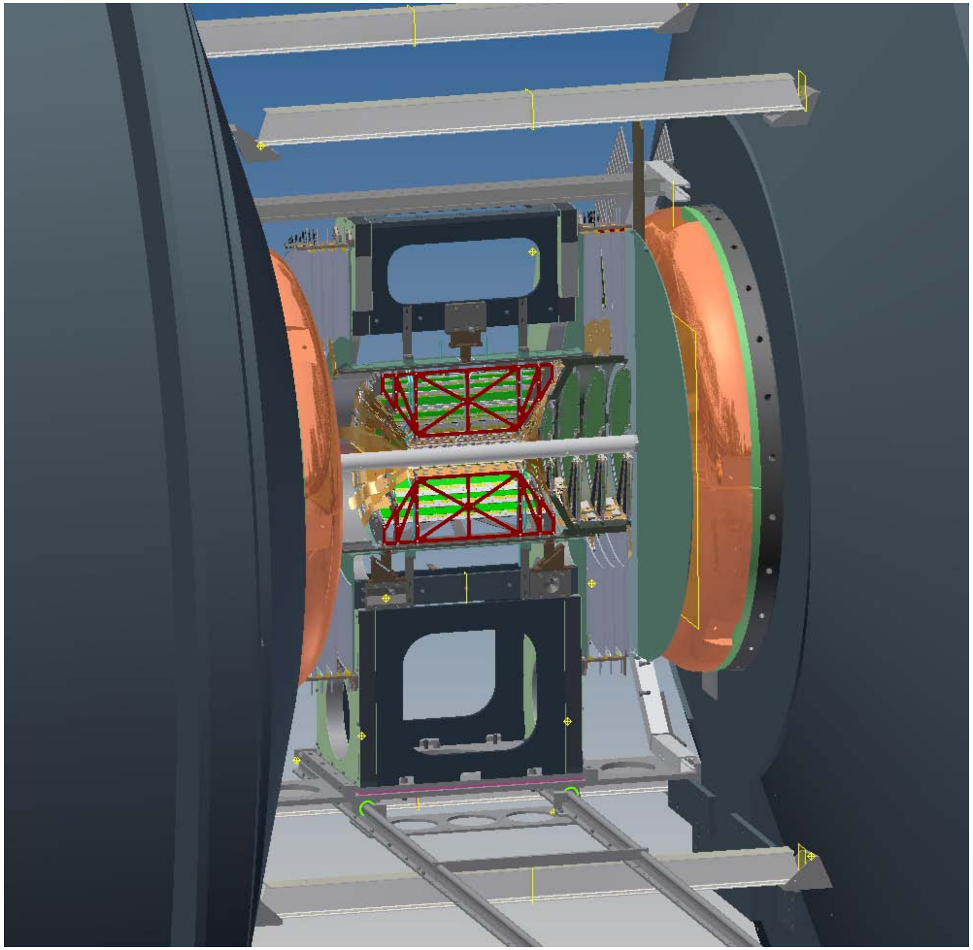


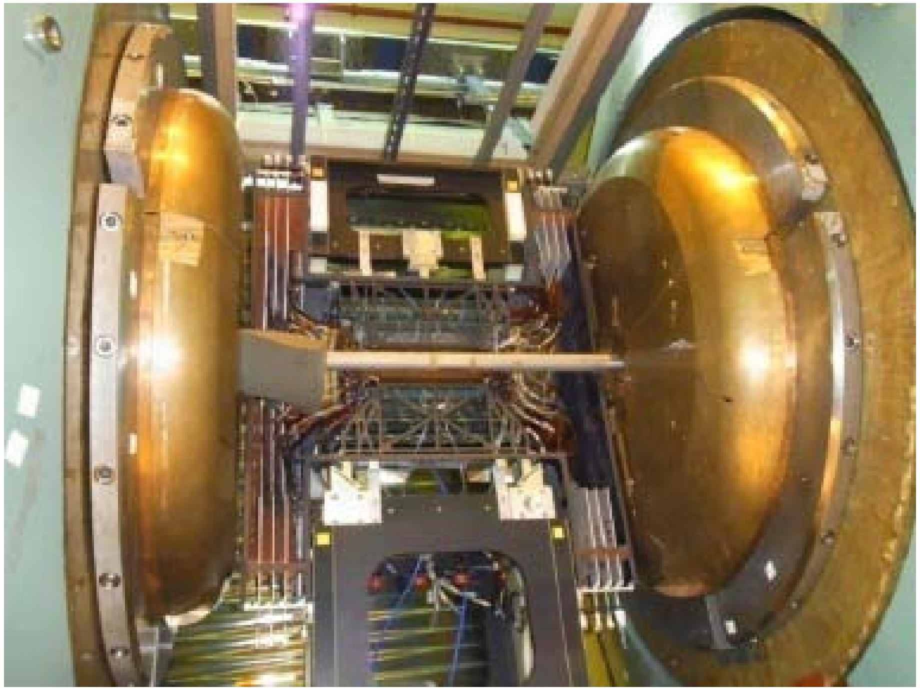
Half VTX assembly being optically surveyed: all ladders to global monuments in assembly. These will again be surveyed in relationship to monuments in the PHENIX hall. Expected detector positioning will be known to ~50. microns in the hall.



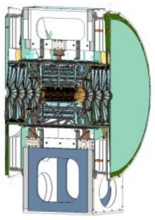
CAD vs. As-Built:



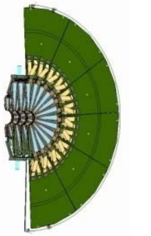




Demonstration of importance of constructing an accurate CAD model of experimental assemblies, installation of VTX proceeded just as modeled without any conflicts.



VTX & FVTX collaboration institutions:



- Brookhaven National Laboratory
- Columbia University
- Ecole-Polytechnique
- Iowa State University
- Kyoto University
- Los Alamos National Laboratory
- New Mexico State University
- Oak Ridge National Laboratory
- RIKEN
- Riken-Brookhaven Research Center
- Stony Brook University
- University of New Mexico